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2.8X0.8mm RIGHT ANGLE SMD CHIP LED **LAMP**

Blue

Part Number: KA-2810AQBS-F



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Features

- 2.8mmX0.8mm right angle SMT LED, 1.2mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

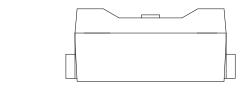
The Blue source color devices are made with InGaN Light Emitting Diode.

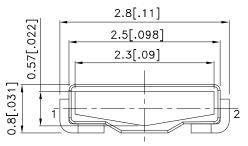
Static electricity and surge damage the LEDS.

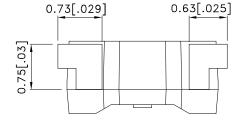
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

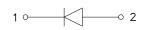
All devices, equipment and machinery must be electrically grounded.

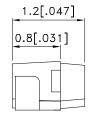
Package Dimensions

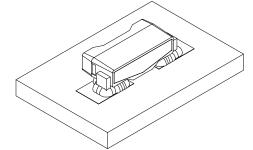












- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.0039") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

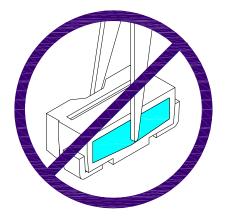
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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated

Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



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Selection Guide

| Part No. | Dice | Lens Type | Iv (mcd) [2] @ 20mA | | Viewing Angle [1] |
|---------------|--------------|---------------------------------------|------------------------|------|----------------------|
| | | , , , , , , , , , , , , , , , , , , , | Min. | Тур. | 201/2 |
| KA-2810AQBS-F | Blue (InGaN) | WATER CLEAR | 110 | 250 | 110° |

Notes

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|--------|------|------|-------|--------------------|
| λpeak | Peak Wavelength | Blue | 461 | | nm | IF=20mA |
| λD [1] | Dominant Wavelength | Blue | 465 | | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Blue | 25 | | nm | IF=20mA |
| С | Capacitance | Blue | 100 | | pF | VF=0V;f=1MHz |
| VF [2] | Forward Voltage | Blue | 3.3 | 4 | V | IF=20mA |
| lR | Reverse Current | Blue | | 50 | uA | V _R =5V |

Notes:

- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

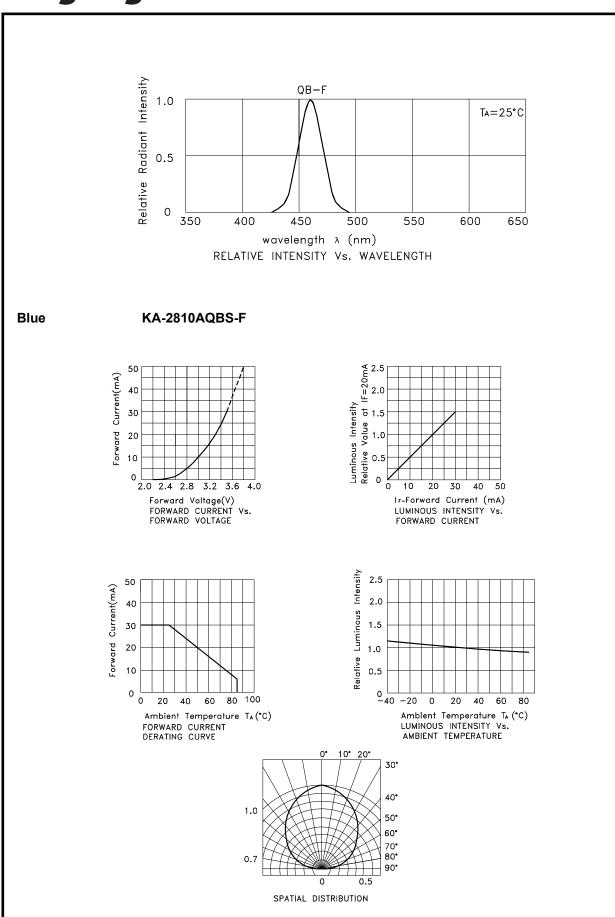
Absolute Maximum Ratings at TA=25°C

| Parameter | Blue | Units | |
|--------------------------|----------------|-------|--|
| Power dissipation | 120 | mW | |
| DC Forward Current | 30 | mA | |
| Peak Forward Current [1] | 150 | mA | |
| Reverse Voltage | 5 | V | |
| Operating Temperature | -40°C To +85°C | | |
| Storage Temperature | -40°C To +85°C | | |

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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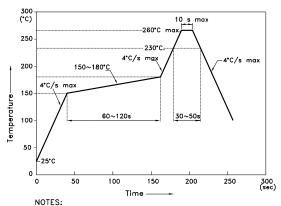


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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



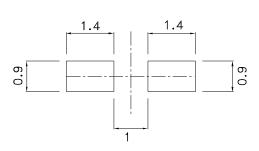
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

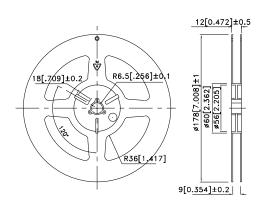
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



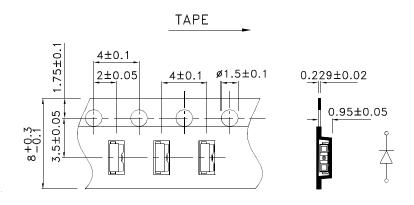
Tape Dimensions (Units: mm)

Reel Dimension

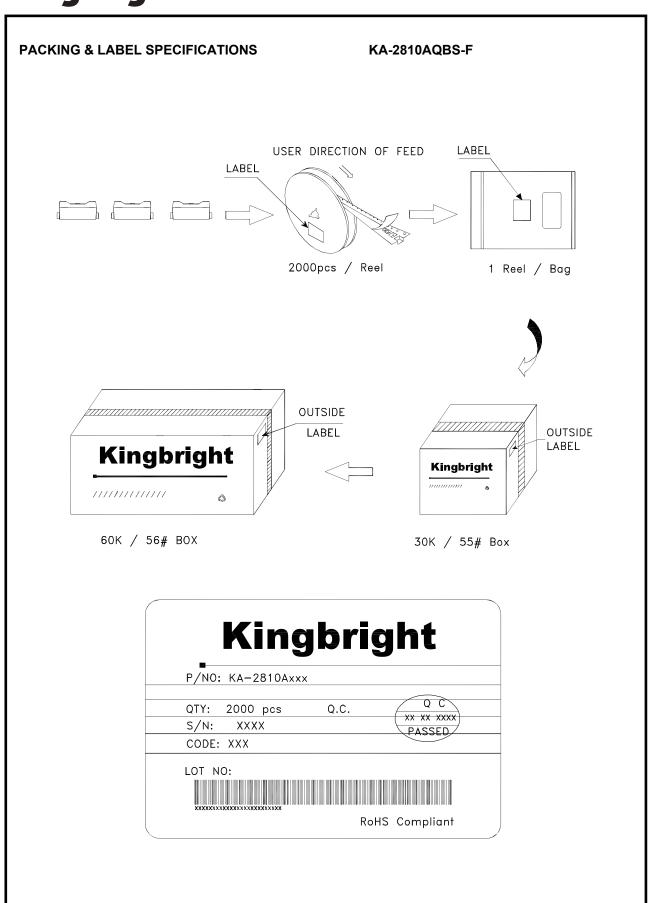


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